
1. A method for making an organic transistor on a substrate comprising the steps of:

providing a substrate including a metal surface layer;

providing a rotatable stamp having relief geometries on its surface to define a stamping surface;

applying a self-assembled monolayer ink to the surface of the rotatable stamp to define an inked stamping surface;

rotating the rotatable stamp on the metal surface layer as the layer is placed in contact with the stamp to impress on the layer an inked pattern as defined by the inked stamping surface; and

patterning the layer by etching material from the layer wherein the inked stamping surface guides the etching in a geometry to define the patterned layer useful in fabricating an electronic device;

removing the inked pattern from the layer; and

applying an organic semiconductor layer overlying the etched metal layer.

Cancel ~~claim~~ 6.

Amend claim 7 to read:

7. The method of claim 6 in which the metal layer includes a thin layer of gold or silver.

Amend claim 8 to read:

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8. The method of claim 1 in which the step of patterning the metal layer comprises etching material from the substrate applying an etchant from the group consisting of aqueous ferrocyanide, $K_4Fe(CN)_6$, $K_3Fe(CN)_6$, $Na_2S_2O_3$, and KOH in H_2O .

☒ Amend claim 9 to read

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9. The method of claim 1, in which the step of rotating the stamp provides an exposed region on the metal layer where substantially no ink is present and a protected region on the layer where ink substantially covers the protected region.

☒ Cancel claim 10.

Amend claim 11 to read:

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11. The method of claim 10, in which the metal layer has an applied adhesive layer selected from the group consisting of Ti and Cr.

Amend claim 12 to read:

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12. The method of claim 1 in which the inked pattern is removed by ultraviolet light, heat, or wet chemical cleaning.